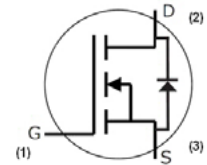


C2M0080120D

Silicon Carbide Power MOSFET C2M™ MOSFET Technology
N-Channel Enhancement Mode

Features

- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low Capacitances
- Easy to Parallel and Simple to Drive
- Avalanche Ruggedness
- Halogen Free, RoHS Compliant



WolfSpeed, Inc. is in the process of rebranding its products and related materials pursuant to the entity name change from Cree, Inc. to WolfSpeed, Inc. During this transition period, products received may be marked with either the Cree name and/or logo or the WolfSpeed name and/or logo.

Ordering Part Number	Package	Marking
C2M0080120D	TO-247-3	C2M0080120D

Typical Applications

- Solar inverters
- Switch Mode Power Supplies
- High voltage DC/DC converters
- Battery Chargers
- Motor Drives
- Pulsed Power applications

Benefits

- Higher System Efficiency
- Reduced Cooling Requirements
- Increased Power Density
- Increase system switching frequency

Key Parameters

Parameter	Symbol	Min.	Typ.	Max	Unit	Conditions	Note
Drain - Source Voltage	V_{DS}			1200	v	$T_c = 25^\circ\text{C}$	
Maximum Gate - Source Voltage	$V_{GS(max)}$	-10		+25		Transient	
Operational Gate-Source Voltage	V_{GSop}		-5/20			Static	Note 1
DC Continuous Drain Current	I_D			36	A	$V_{GS} = 20\text{ V}, T_c = 25^\circ\text{C}, T_J \leq 150^\circ\text{C}$	Fig. 19
				24		$V_{GS} = 20\text{ V}, T_c = 100^\circ\text{C}, T_J \leq 150^\circ\text{C}$	Note 2
Pulsed Drain Current	I_{DM}			80		t_{Pmax} limited by T_{Jmax} $V_{GS} = 20\text{ V}, T_c = 25^\circ\text{C}$	Fig. 22
Power Dissipation	P_D			192	W	$T_c = 25^\circ\text{C}, T_J = 150^\circ\text{C}$	Fig. 20
Operating Junction and Storage Temperature	T_J, T_{stg}			-55 to +150	°C		
Solder Temperature	T_L			260		According to JEDEC J-STD-020	
Mounting Torque	M_D			1 8.8	Nm lbf-in	M3 or 6-32 screw	

Note (1): Recommended turn-on gate voltage is 20V with $\pm 5\%$ regulation tolerance, see Application Note PRD-04814 for additional details

Note (2): Verified by design



Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions	Note
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	1200	—	—	V	$V_{GS} = 0\text{ V}, I_D = 100\ \mu\text{A}$	
Gate Threshold Voltage	$V_{GS(th)}$	2.0	2.9	4		$V_{DS} = V_{GS}, I_D = 5\text{ mA}$	Fig. 11
Zero Gate Voltage Drain Current	I_{DSS}	—	1	100	μA	$V_{DS} = 1200\text{ V}, V_{GS} = 0\text{ V}$	
Gate-Source Leakage Current	I_{GSS}	—	—	250	nA	$V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$	
Drain-Source On-State Resistance	$R_{DS(on)}$	—	80	98	m Ω	$V_{GS} = 20\text{ V}, I_D = 20\text{ A}$	Fig. 4, 5, 6
		—	144	—		$V_{GS} = 20\text{ V}, I_D = 20\text{ A}, T_J = 150^\circ\text{C}$	
Transconductance	g_{fs}	—	10	—	S	$V_{DS} = 20\text{ V}, I_{DS} = 20\text{ A}$	Fig. 7
		—	9	—		$V_{DS} = 20\text{ V}, I_{DS} = 20\text{ A}, T_J = 150^\circ\text{C}$	
Input Capacitance	C_{iss}	—	1130	—	pF	$V_{GS} = 0\text{ V}$ $V_{DS} = 1000\text{ V}$ $f = 1\text{ MHz}$ $V_{AC} = 25\text{ mV}$	Fig. 17, 18
Output Capacitance	C_{oss}	—	92	—			
Reverse Transfer Capacitance	C_{rss}	—	7.5	—			
C_{oss} Stored Energy	E_{oss}	—	50	—			
Avalanche Energy, Single Pluse	E_{AS}	—	1	—	J	$I_D = 20\text{ A}, V_{DD} = 50\text{V}$	Fig. 29
Turn-On Switching Energy	E_{on}	—	523	—	μJ	$V_{DS} = 800\text{ V}, V_{GS} = -5\text{ V}/20\text{ V}$, $I_D = 20\text{ A}, R_{G(ext)} = 2.5\ \Omega, L = 156\ \mu\text{H}$	Fig. 25
Turn-Off Switching Energy	E_{off}	—	72	—			
Turn-On Delay Time	$t_{d(on)}$	—	15	—	ns	$V_{DD} = 800\text{ V}, V_{GS} = -5\text{ V}/20\text{ V}$ $I_D = 20\text{ A}, R_{G(ext)} = 2.5\ \Omega, R_L = 40\ \Omega$, Timing relative to V_{DS} Per IEC60747-8-4 pg 83	Fig. 27
Rise Time	t_r	—	22	—			
Turn-Off Delay Time	$t_{d(off)}$	—	24	—			
Fall Time	t_f	—	14	—			
Internal Gate Resistance	$R_{G(int)}$	—	3.9	—	Ω	$f = 1\text{ MHz}, V_{AC} = 25\text{ mV}$	
Gate to Source Charge	Q_{GS}	—	17	—	nC	$V_{DS} = 800\text{ V}, V_{GS} = -5/20\text{ V}$ $I_D = 20\text{ A}$ Per IEC60747-8-4 pg 21	Fig. 12
Gate to Drain Charge	Q_{GD}	—	29	—			
Total Gate Charge	Q_g	—	71	—			

Reverse Diode Characteristics

Parameter	Symbol	Typ.	Max.	Unit	Test Conditions	Notes
Diode Forward Voltage	V_{SD}	4.3	—	V	$V_{GS} = -5\text{ V}, I_{SD} = 10\text{ A}$	Fig. 8, 9, 10
Diode Forward Voltage		3.8	—		$V_{GS} = -5\text{ V}, I_{SD} = 10\text{ A}, T_J = 150^\circ\text{C}$	
Continuous Diode Forward Current ¹	I_S	—	36	A	$T_c = 25^\circ\text{C}$	Note 1
Reverse Recovery Time ¹	t_{rr}	24	—	ns	$V_{GS} = -5\text{ V}, I_{SD} = 20\text{ A}, V_R = 800\text{ V}$ $di_F/dt = 1950\text{ A}/\mu\text{s}$	Note 1
Reverse Recovery Charge ¹	Q_{rr}	152	—	nC		
Peak Reverse Recovery Current ¹	I_{RRM}	10	—	A		

Note:

¹ When using SiC Body Diode the maximum recommended $V_{GS} = -5\text{V}$

Thermal Characteristics

Parameter	Symbol	Typ	Max.	Unit	Note
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.60	0.65	$^\circ\text{C}/\text{W}$	Fig. 21
Thermal Resistance From Junction to Ambient	$R_{\theta JA}$	—	40		



Typical Performance

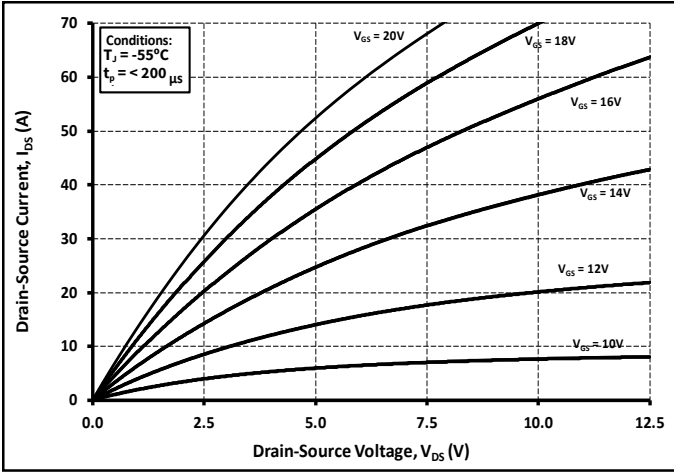


Figure 1. Output Characteristics $T_J = -55^\circ\text{C}$

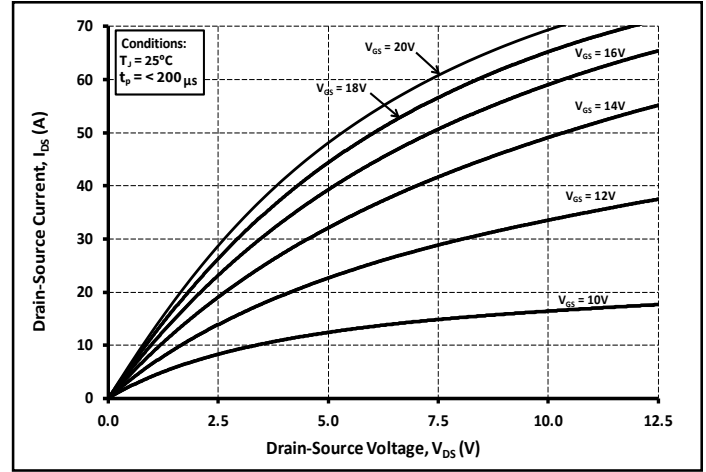


Figure 2. Output Characteristics $T_J = 25^\circ\text{C}$

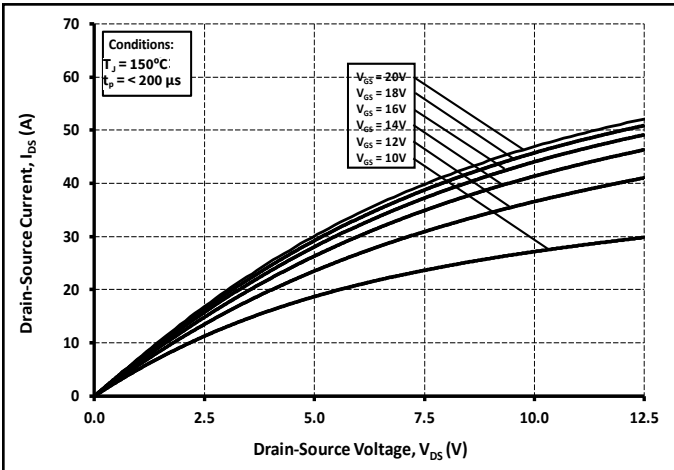


Figure 3. Output Characteristics $T_J = 150^\circ\text{C}$

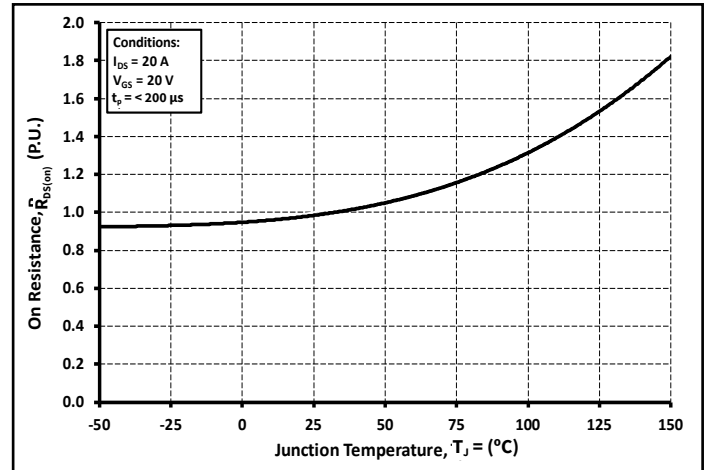


Figure 4. Normalized On-Resistance vs. Temperature

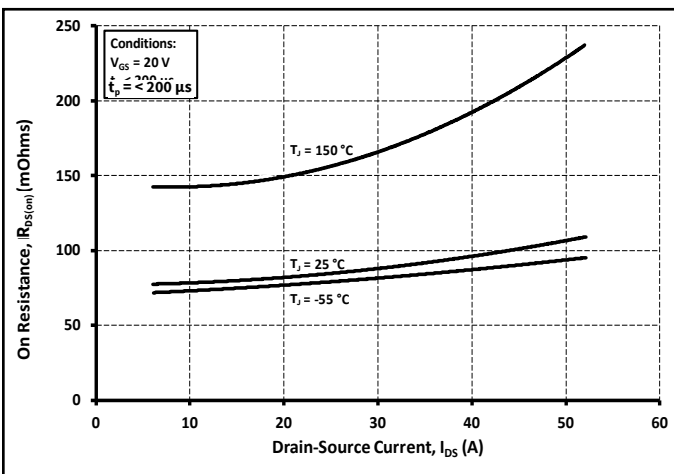


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

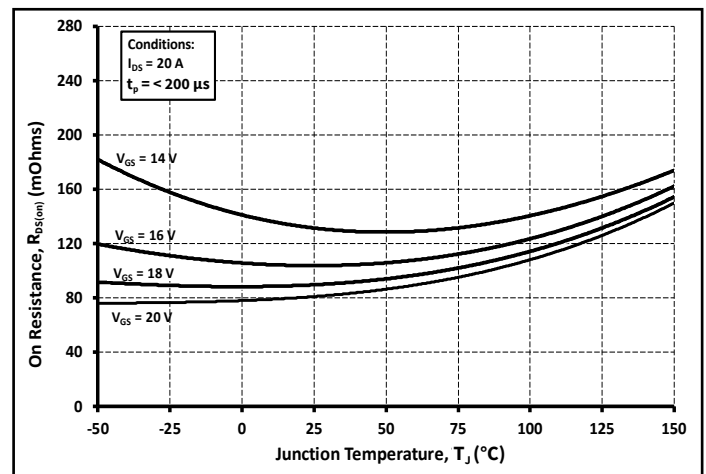


Figure 6. On-Resistance vs. Temperature For Various Gate Voltage



Typical Performance

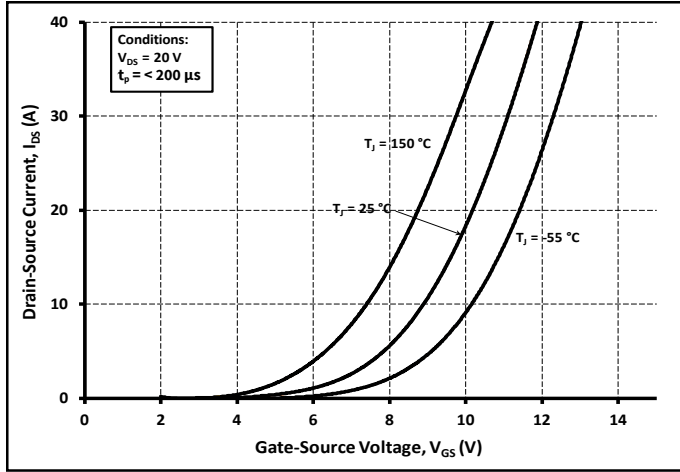


Figure 7. Transfer Characteristic For Various Junction Temperatures

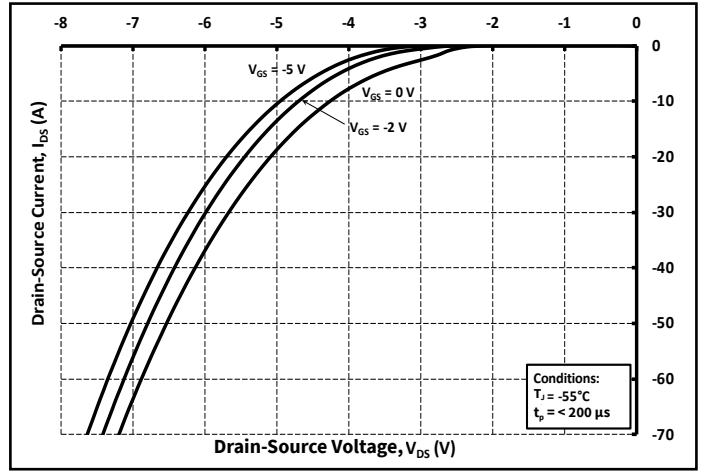


Figure 8. Body Diode Characteristic at -55°C

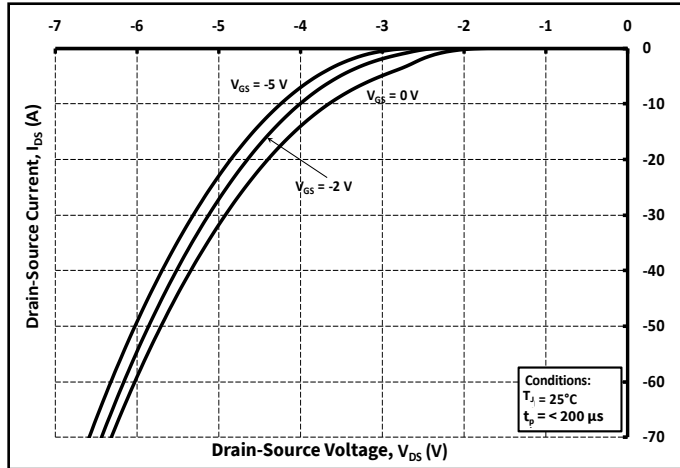


Figure 9. Body Diode Characteristic at 25°C

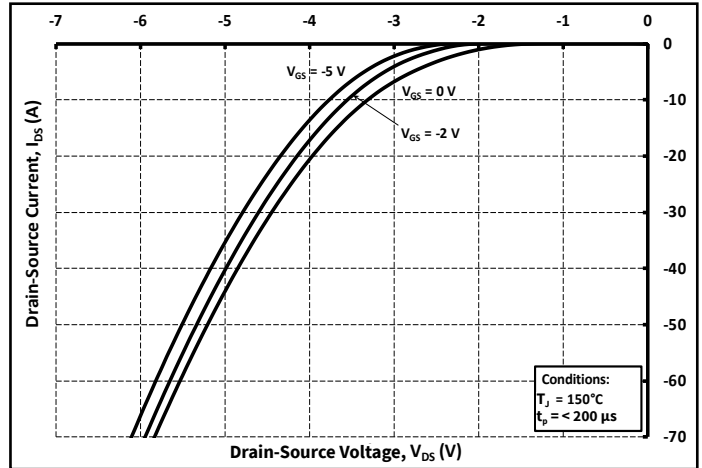


Figure 10. Body Diode Characteristic at 150°C

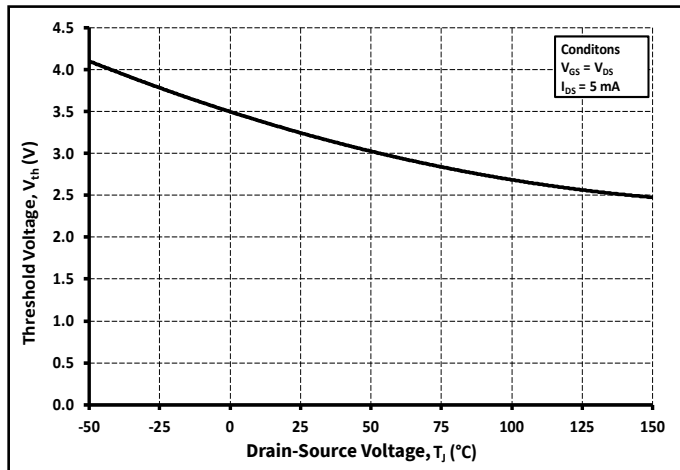


Figure 11. Threshold Voltage vs. Temperature

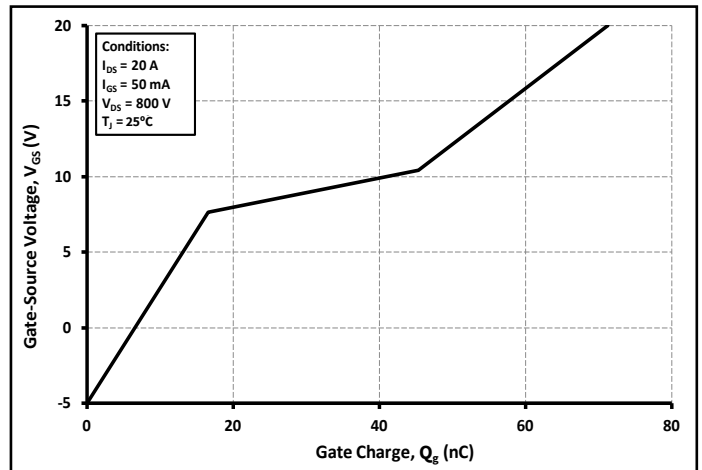


Figure 12. Gate Charge Characteristics



Typical Performance

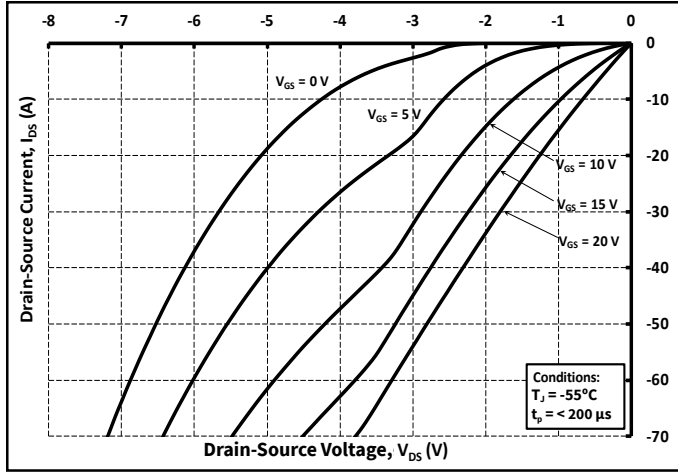


Figure 13. 3rd Quadrant Characteristic at -55°C

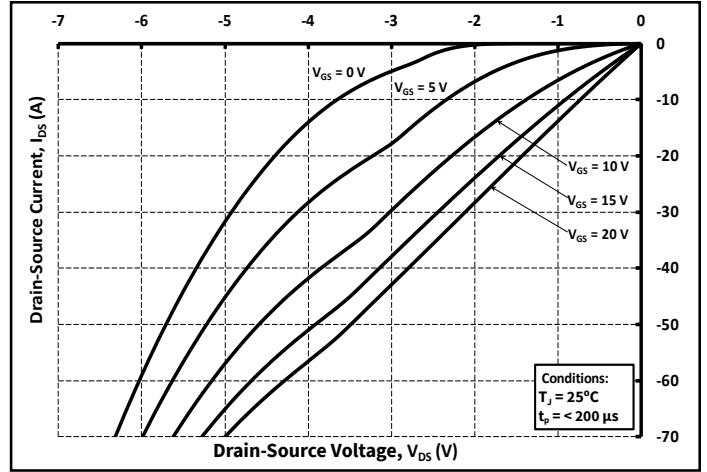


Figure 14. 3rd Quadrant Characteristic at 25°C

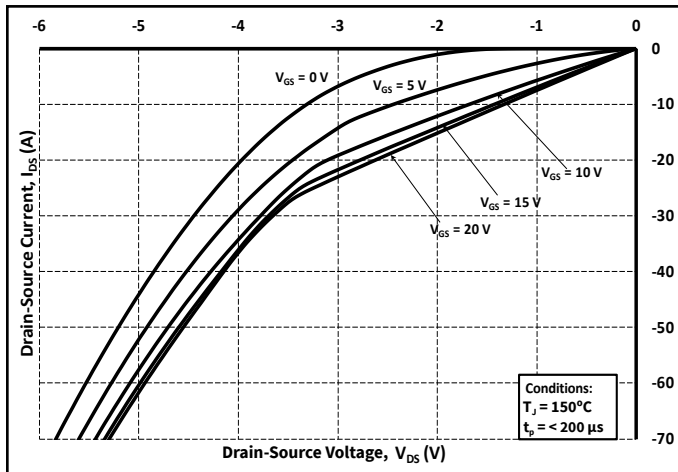


Figure 15. 3rd Quadrant Characteristic at 150°C

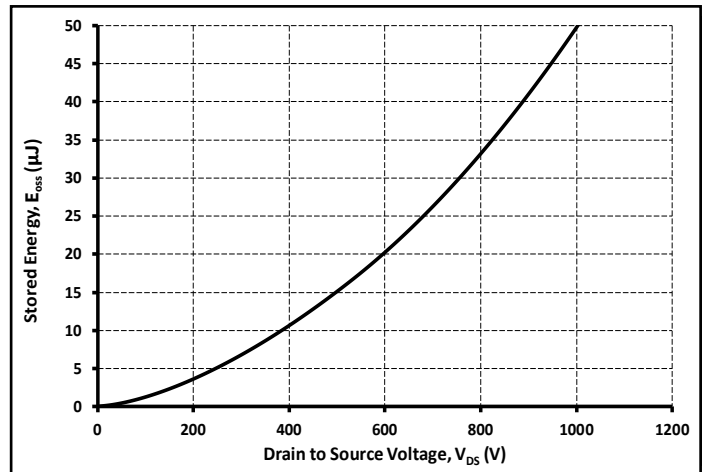


Figure 16. Output Capacitor Stored Energy

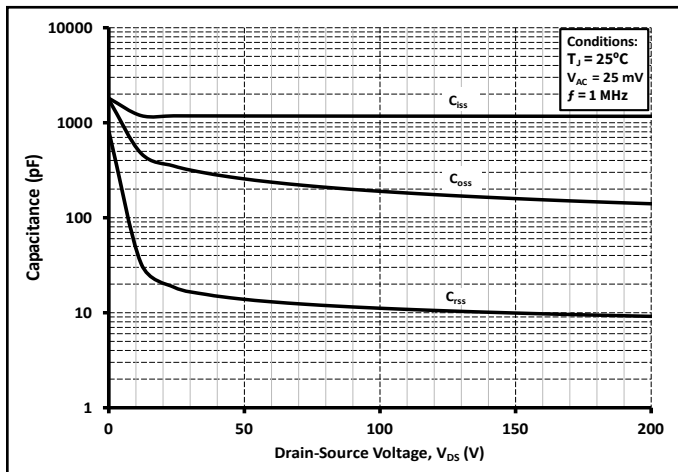


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200 V)

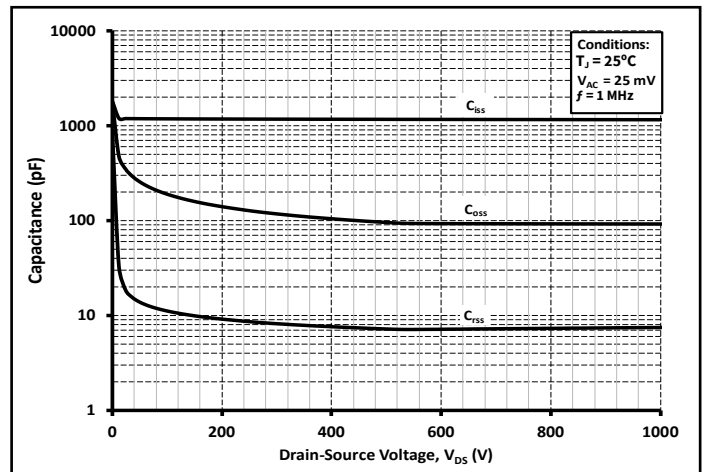


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1000 V)



Typical Performance

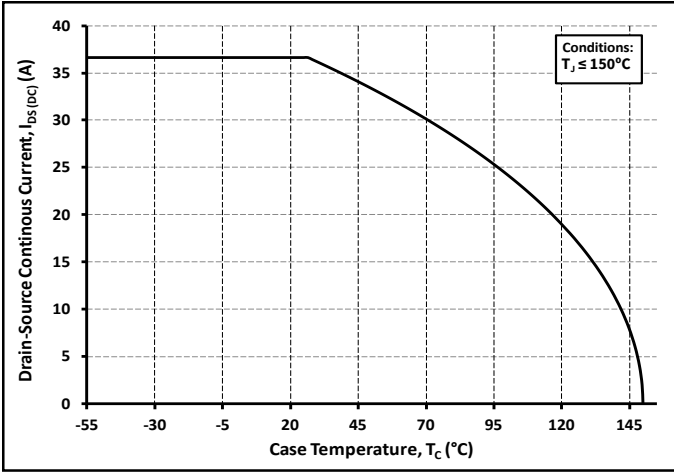


Figure 19. Continuous Drain Current Derating vs. Case Temperature

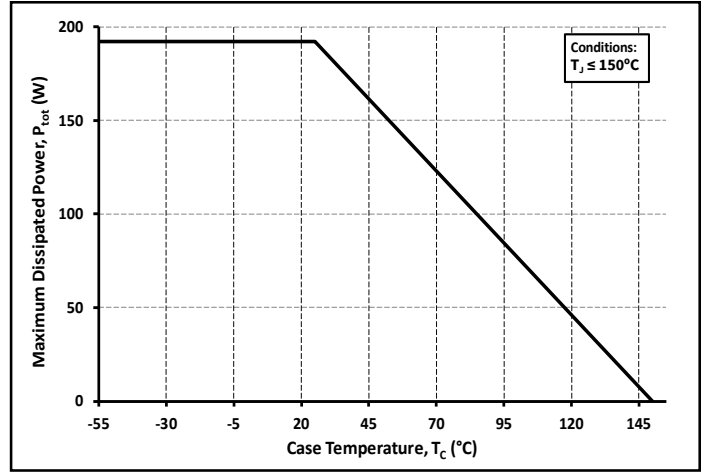


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

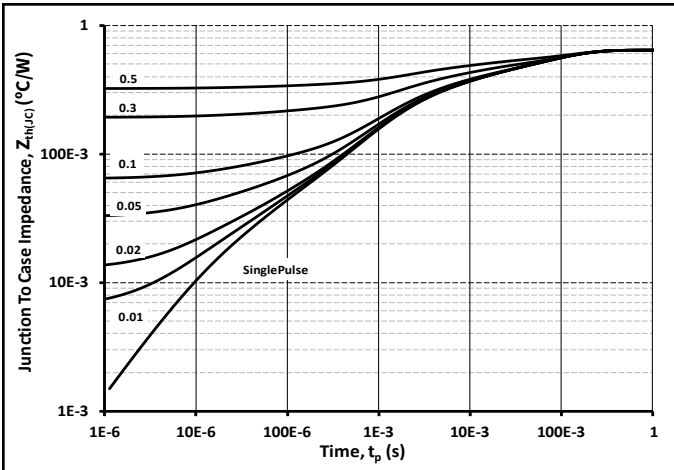


Figure 21. Transient Thermal Impedance (Junction - Case)

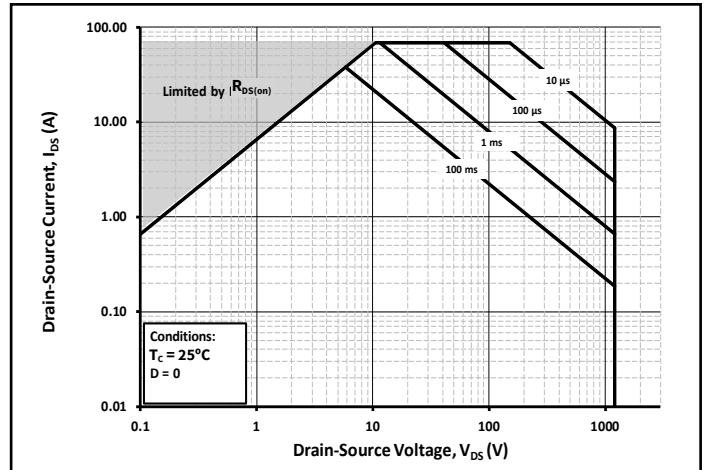


Figure 22. Safe Operating Area

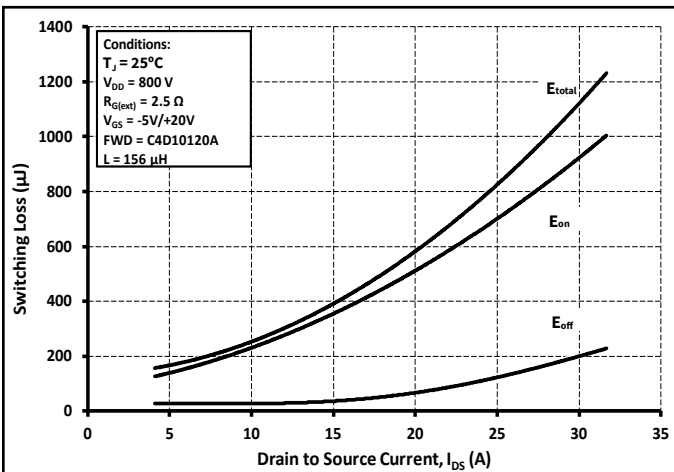


Figure 23. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 600\text{ V}$)

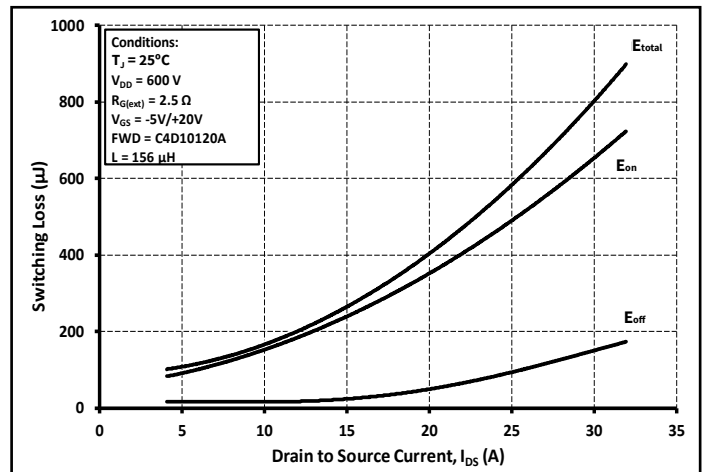


Figure 24. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 800\text{ V}$)



Typical Performance

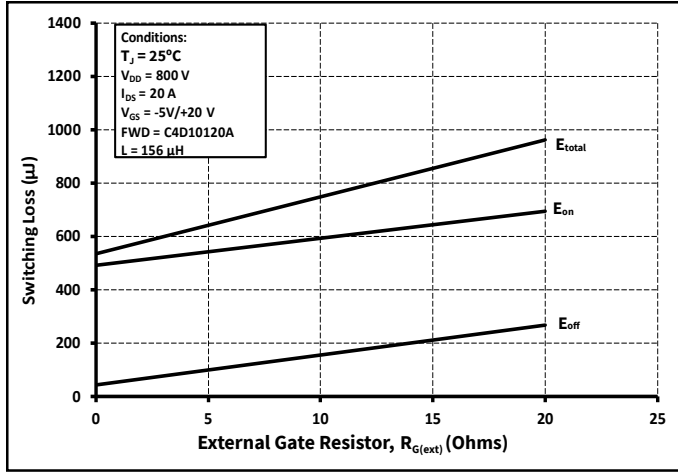


Figure 25. Clamped Inductive Switching Energy vs $R_{G(ext)}$

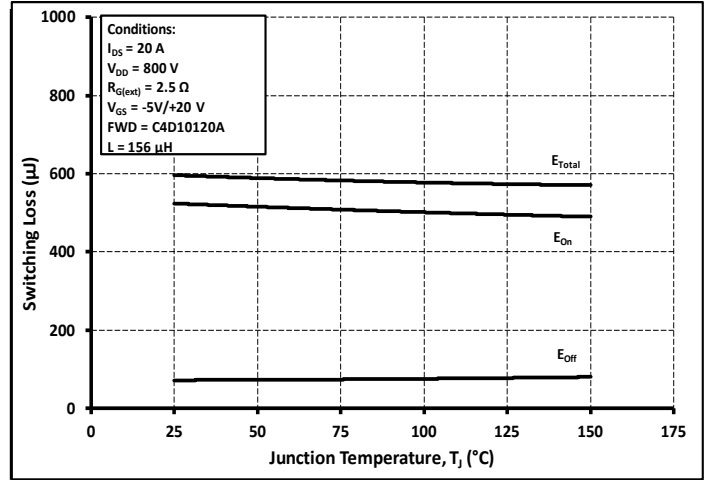


Figure 26. Clamped Inductive Switching Energy vs. Temperature

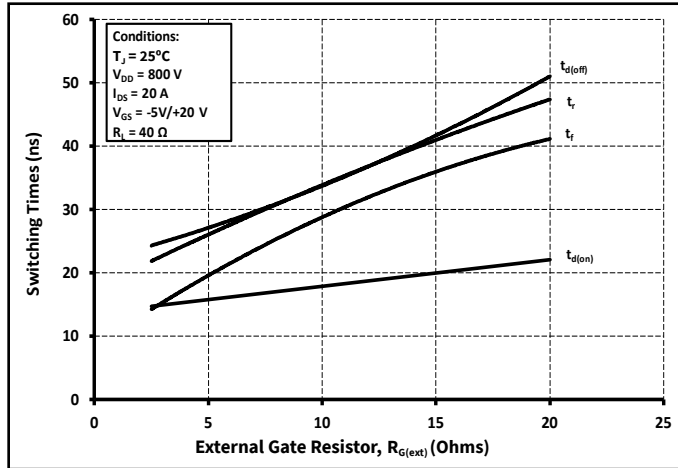


Figure 27. Switching Times vs. $R_{G(ext)}$

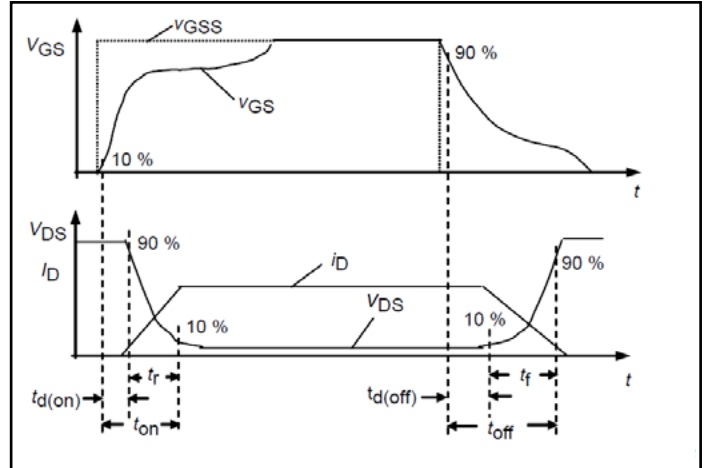


Figure 28. Switching Times Definition

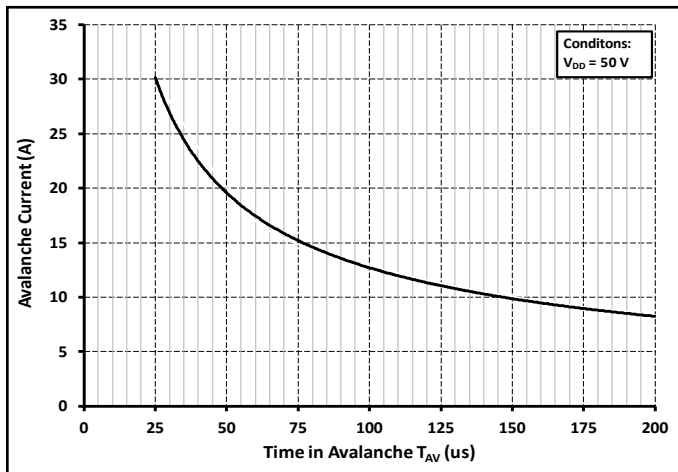


Figure 29. Single Avalanche SOA curve

Test Circuit Schematic

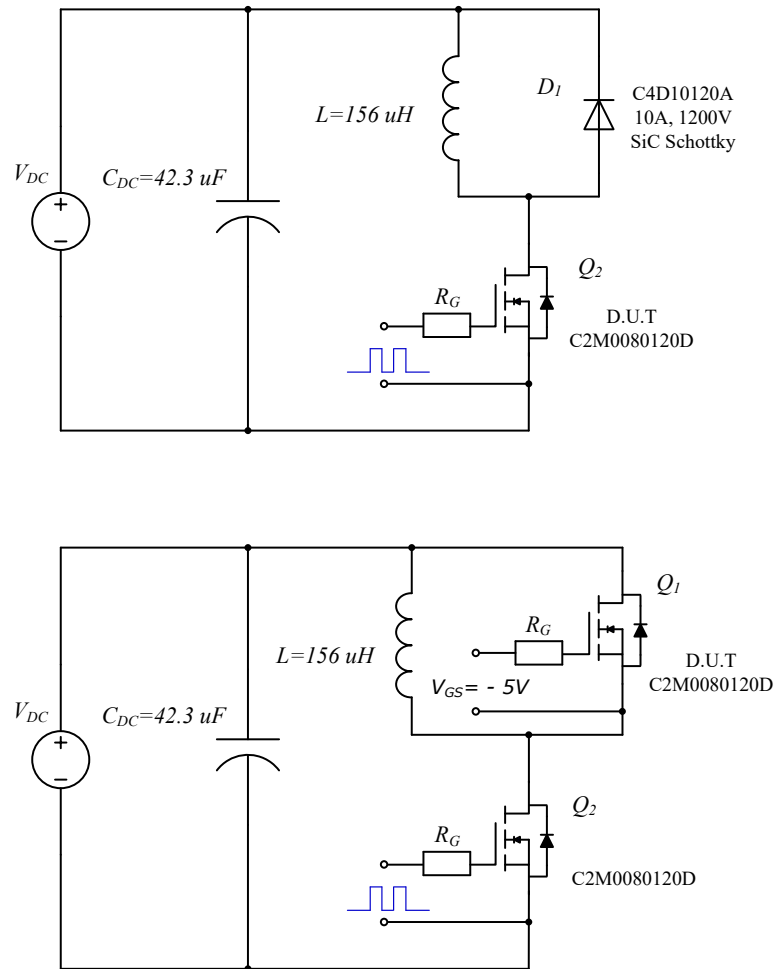
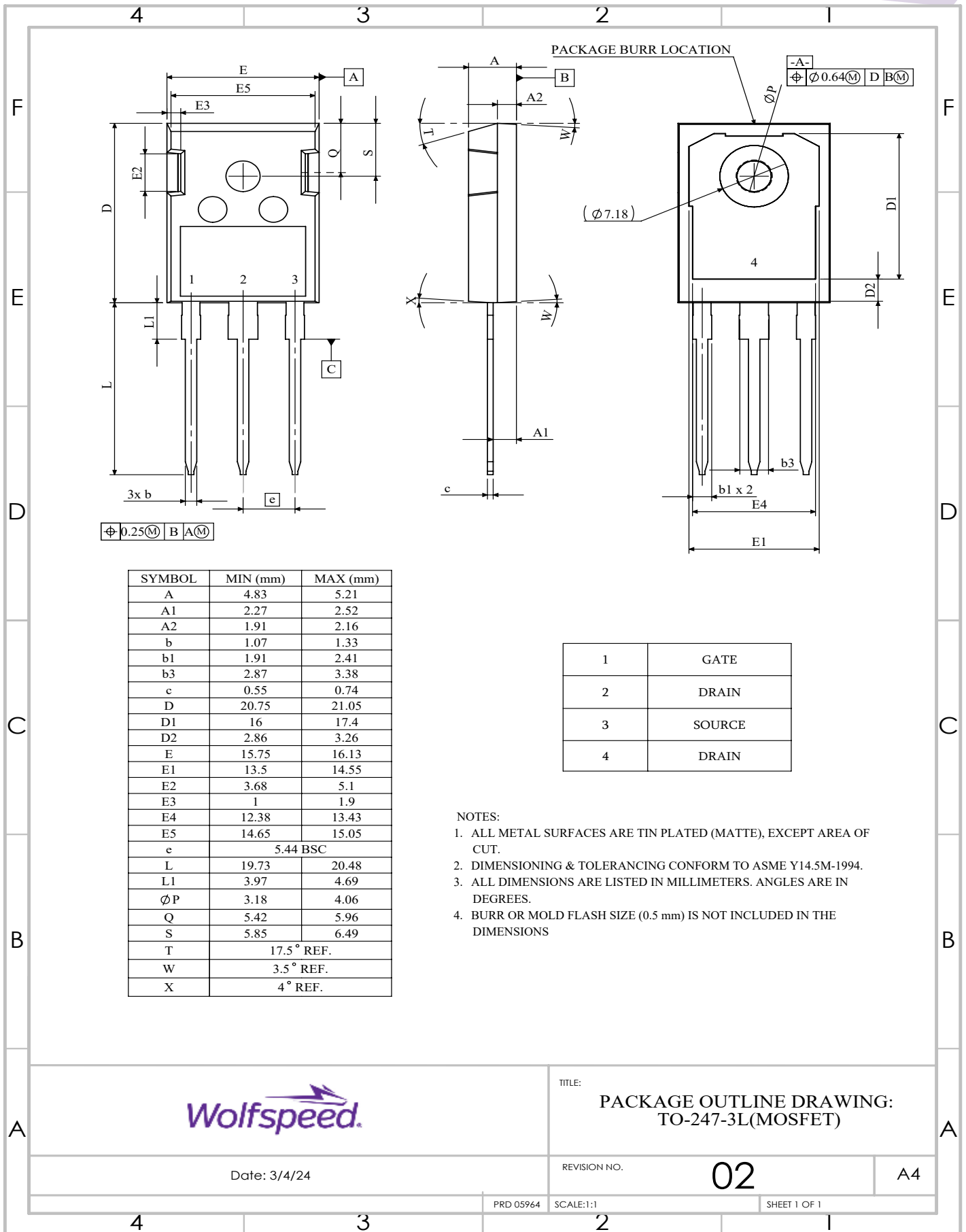


Figure 31. Body Diode Recovery Test Circuit

Package Dimensions - TO-247-3L



$\phi 0.25(M) B A(M)$

SYMBOL	MIN (mm)	MAX (mm)
A	4.83	5.21
A1	2.27	2.52
A2	1.91	2.16
b	1.07	1.33
b1	1.91	2.41
b3	2.87	3.38
c	0.55	0.74
D	20.75	21.05
D1	16	17.4
D2	2.86	3.26
E	15.75	16.13
E1	13.5	14.55
E2	3.68	5.1
E3	1	1.9
E4	12.38	13.43
E5	14.65	15.05
e	5.44 BSC	
L	19.73	20.48
L1	3.97	4.69
ϕP	3.18	4.06
Q	5.42	5.96
S	5.85	6.49
T	17.5° REF.	
W	3.5° REF.	
X	4° REF.	

1	GATE
2	DRAIN
3	SOURCE
4	DRAIN

NOTES:

1. ALL METAL SURFACES ARE TIN PLATED (MATTE), EXCEPT AREA OF CUT.
2. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
3. ALL DIMENSIONS ARE LISTED IN MILLIMETERS. ANGLES ARE IN DEGREES.
4. BURR OR MOLD FLASH SIZE (0.5 mm) IS NOT INCLUDED IN THE DIMENSIONS



TITLE:

PACKAGE OUTLINE DRAWING:
TO-247-3L(MOSFET)

Date: 3/4/24

REVISION NO.

02

A4

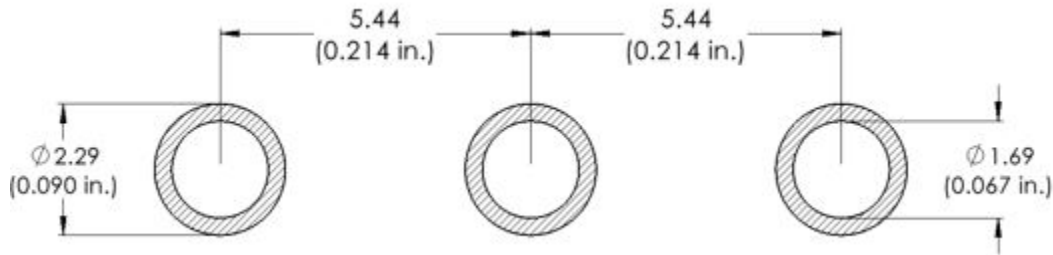
PRD 05964

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SHEET 1 OF 1



Recommended Solder Pad Layout



Revision History

Current Revision	Date of Release	Description of Changes
D	September-2019	N/A
5	November-2023	Updated Wolfspeed branding, package drawing, package image, and solder pad layout, added Revision History Table
6	October - 2024	Legal Disclaimer, POD, Table 1 Layout

Related Links

- [SPICE Models](http://wolfspeed.com/power/tools-and-support): <http://wolfspeed.com/power/tools-and-support>
- [SiC MOSFET Isolated Gate Driver Reference Design](http://wolfspeed.com/power/tools-and-support): <http://wolfspeed.com/power/tools-and-support>
- [SiC MOSFET Evaluation Board](http://wolfspeed.com/power/tools-and-support): <http://wolfspeed.com/power/tools-and-support>



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This product has not been designed or tested for use in, and is not intended for use in, any application in which failure of the product would reasonably be expected to cause death, personal injury, or property damage. For purposes of (but without limiting) the foregoing, this product is not designed, intended, or authorized for use as a critical component in equipment implanted into the human body, life-support machines, cardiac defibrillators, and similar emergency medical equipment; air traffic control systems; or equipment used in the planning, construction, maintenance, or operation of nuclear facilities. Notwithstanding any application-specific information, guidance, assistance, or support that Wolfspeed may provide, the buyer of this product is solely responsible for determining the suitability of this product for the buyer’s purposes, including without limitation (1) selecting the appropriate Wolfspeed products for the buyer’s application, (2) designing, validating, and testing the buyer’s application, and (3) ensuring the buyer’s application meets applicable standards and any other legal, regulatory, and safety-related requirements.

RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Wolfspeed representative or from the Product Documentation sections of www.wolfspeed.com.

REACH Compliance

REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact your Wolfspeed representative to ensure you get the most up-to-date REACH SVHC Declaration. REACH banned substance information (REACH Article 67) is also available upon request. SVHC Declaration. REACH banned substance information (REACH Article 67) is also available upon request.

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